ABSTRACT

DIE BONDING METHOD UTILIZING ROTARY WAFER TABLE

An array of semiconductor components, comprising a first plurality of semiconductor components and a second plurality of semiconductor components held on a carrier, is bonded onto one or more substrates. The first plurality of semiconductor components is first located for pick-up by a transfer device, and each semiconductor component comprised in the first plurality of semiconductor components is picked up with the transfer device and is bonded onto a respective bonding position on the one or more substrates. After the first plurality of semiconductor components have been picked up and bonded, the carrier is rotated and the second plurality of semiconductor components is located for pick-up by the transfer device. Thereafter, each semiconductor component comprised in the second plurality of semiconductor components is picked up with the transfer device and is bonded onto a respective bonding position on the one or more substrates.

(FIG. 2)